

## **CRYSTAL OSCILLATOR (SPXO)**

**OUTPUT: HCSL** 





**Product Number** SG2016HGN:X1G006221xxxx15 SG2520HGN:X1G005891xxxx15

## **SG2016HGN / SG2520HGN**

25 MHz to 500 MHz •Frequency range Supply voltage 2.5 V Typ. / 3.3 V Typ. •Frequency tolerance  $\pm 25 \times 10^{-6}, \pm 50 \times 10^{-6}$ 

-40 °C to +85 °C, -40 °C to +105 °C •Operating temperature range Function Output enable (OE) or Standby (ST)

 Phase jitter 90 fs Max.

 $(100 \text{ MHz} < \text{fo} \le 156 \text{ MHz}, V_{CC} = 2.5 \text{ V}, 3.3 \text{ V})$ 



SG2016HGN  $(2.0 \times 1.6 \times 0.63 \text{ mm})$ 



SG2520HGN  $(2.5 \times 2.0 \times 0.74 \text{ mm})$ 

PCIe Gen5,6 Jitter specification compliant. Specifications (characteristics)

Item	Symbol	Specifications	Condition	s / Remarks	
Output frequency range	fo	25 MHz to 500 MHz	Please contact us for availa	able frequencies.	
Supply voltage	V <sub>cc</sub>	D: 2.5 V ± 5 %, C: 3.3 V ± 5 %			
Storage temperature range	T_stg	-55 °C to +125 °C			
Operating temperature range	T use	G: -40 °C to +85 °C, H: -40 °C to +105 °C			
	_	D: ±25 × 10-6 Max	Includes initial frequency to		
Frequency tolerance	f_tol	J: ±50 × 10 <sup>-6</sup> Max.	temperature characteristics		
			coefficient and 10 years ag		
Current consumption	Icc	35 mA Max.	25 MHz ≤ fo < 212 MHz	OE or $\overline{ST} = V_{CC}$ ,	
'		40 mA Max.	212 MHz ≤ fo < 500 MHz	L_HCSL = $50 \Omega$	
Disable current	I_dis	25 mA Max.	OE = GND		
Stand-by current	I_std	30 μA Max.	ST = GND, T_use Max. = +		
Stand-by current	1_5tu	60 μA Max.	ST = GND, T_use Max. = +	·105 °C	
Symmetry	SYM	45 % to 55 %	At output crossing point		
		0.5 V to 0.7 V	25 MHz ≤ fo < 212 MHz	Output option: A	
	V <sub>OH</sub>	0.4 V to 0.65 V	212 MHz ≤ fo < 500 MHz	Output option. A	
Output voltage	VOH	0.6 V to 0.8 V	25 MHz ≤ fo < 212 MHz	Outrot antique D	
		0.5 V to 0.75 V	212 MHz ≤ fo < 500 MHz	Output option: B	
	V <sub>OL</sub>	-0.15 V to +0.15 V			
D:# :: 1 :	.,	0.7 V to 1.4 V	Output option: A		
Differential swing	Vsw	0.8 V to 1.6 V	Output option: B		
Crossing voltage	V <sub>CR</sub>	0.25 V to 0.55 V			
Rise time / Fall time	tr/tf	0.7 ns Max.	20 % - 80 % (V <sub>OH</sub> - V <sub>OL</sub> )		
Differential output rise slew rate / fall slew rate	Rr/Rf	2 V/ns to 10 V/ns	Between -0.15 V and 0.15	V of differential output	
Output load condition	L_HCSL	50 Ω			
I	V <sub>IH</sub>	70 % V <sub>CC</sub> Min.	OE or ST terminal		
Input voltage	VIL	30 % V <sub>CC</sub> Max.	OE of ST terminal		
Output enable time	tsta_oe	500 ns Max.	t = 0 at OE = 70 % V <sub>CC</sub>		
Output enable time	tsta_st	10 ms Max.	t = 0 at \$\overline{ST}\$ = 70 % V <sub>CC</sub>		
	tstp_oe	100 ns Max.	t = 0 at OE = 30 % V <sub>CC</sub>	t = 0 at OE = 30 % V <sub>CC</sub>	
Output disable time	tstp_st	100 ns Max.	t = 0 at \$\overline{ST}\$ = 30 % V <sub>CC</sub>	t = 0 at ST = 30 % V <sub>CC</sub>	
Start-up time	t str	10 ms Max.	t = 0 at 90 % V <sub>CC</sub>		
Phase jitter		200 fs Max.	25 MHz ≤ fo < 100 MHz	Offset frequency	
		90 fs Max.	100 MHz ≤ fo ≤ 156 MHz	fo < 50 MHz:	
	t <sub>PJ</sub>	70 fs Max.	156 MHz < fo ≤ 212 MHz	12 kHz to 5 MHz	
		60 fs Max.	212 MHz < fo ≤ 391 MHz	fo ≥ 50 MHz:	
		50 fs Max.	391 MHz < fo ≤ 500 MHz	12 kHz to 20 MHz	
Jitter	t <sub>c-c</sub>	60 ps Max.	Cycle to cycle jitter (Peak to	Peak)	
PCIe jitter limits		0.1 ps Max.	For PCIe Gen5	,	
for CC architecture	_	0.06 ps Max.	For PCIe Gen6		

## Product name

**Product Name** (Standard form)

SG2520HGN

a: Model b: Output (H: HCSL) c: Frequency d: Supply voltage e: Frequency tolerance

f: Operating temperature g: Function h: Output disable type (Z: High impedance) i: Output option

d: S	Supply voltage
C	3.3 V Typ.
D	2.5 V Typ.

e: F	req. tolerance
D	±25 × 10 <sup>-6</sup>
J	±50 × 10 <sup>-6</sup>

f: O	f: Operating temp.	
G		
Н	-40 °C to +105 °C	

g: F	unction
Р	OE
S	S₹

i: O	utput option
Α	Vsw = 0.7 V to 1.4 V
В	Vsw = 0.8 V to 1.6 V

(Unit:mm)

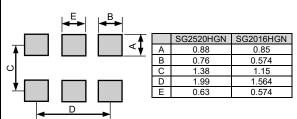
## External dimensions

## (Unit:mm) SG2016HGN

Pin	map	
	Pin	Connection
	1	OE or ST
	2	N.C. (Open or V <sub>CC</sub> )
	3	GND
	4	OUT
	5	OUT
	6	Vcc

OE or  $\overline{ST}$  pin = HIGH or "Open": Specified frequency output. OE or  $\overline{ST}$  pin = LOW: Output is high impedance

## Footprint (Recommended)



In order to achieve optimum jitter performance, it is recommended that  $0.1\,\mu F$  and  $10\,\mu F$  bypass capacitors should be connected between  $V_{CC}$ and GND and placed as close to the  $V_{\text{CC}}$  pin as possible.

# PROMOTION OF ENVIRONMENTAL MANAGEMENT SYSTEM CONFORMING TO INTERNATIONAL STANDARDS

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All of our major manufacturing and non-manufacturing sites, in Japan and overseas, completed the acquisition of ISO 14001 certification.

ISO 14000 is an international standard for environmental management that was established by the International Standards Organization in 1996 against the background of growing concern regarding global warming, destruction of the ozone layer, and global deforestation.

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►Pb free.



► Complies with EU RoHS directive.

\*About the products without the Pb-free mark.

Contains Pb in products exempted by EU RoHS directive.

(Contains Pb in sealing glass, high melting temperature type solder or other.)



▶ Designed for automotive applications such as Car Multimedia, Body Electronics, Remote Keyless Entry etc.



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